

# **COOL POWER TECHNOLOGIES**

# **Eighth-Brick Isolated DC/DC Converter**

### Features

- Wide input voltage range: 36 75Vin
- Output: 1.2V at 30A, 36W max.
- High Efficiency 84% Typical @ FL
- ROHS II Directive 2011/65/EU Compliant
- No minimum load required
- Low height 0.465" (11.8mm) max.
- Baseplate Optional 0.500" (12.7mm) tall
- Basic Insulation
- Withstands 100 V input transients
- Fixed-frequency operation
- Industry standard 8th brick footprint
- Full protection (OTP, OCP, OVP, UVLO auto-restart)
- Remote ON/OFF positive or negative enable logic
- Remote sense
- Weight: 0.79 oz [22.4 g]
- On-board input differential LC-filter
- Meets UL94, V-0 flammability rating
- Output voltage trim range: +20% / -10% (industry-standard trim equations)
- Certified to UL/CSA60950-1, TUV per IEC/EN60950-1, 2<sup>nd</sup> edition
- Compliant to REACH (EC) No 1907/2006
- Designed to meet Class B conducted emissions per FCC and EN55022 when used with external filter (see EMC Compliance section below.)

## Description

The CPE30K48 "Cool Power Technologies" DC-DC converter is an eighth-brick DC-DC converter that conforms to industry standard specifications. The converter operates over an input voltage range of 36 to 75 VDC, and provides a tightly regulated output voltage with an output current rating of 30 A. The output is fully isolated from the input and the converter meets Basic Insulation requirements. The standard feature set includes remote On/Off (positive or negative enable), input undervoltage lockout, output overvoltage protection, overcurrent and short circuit protections, output voltage trim, remote sense and overtemperature shutdown with hysteresis. The high efficiency of the CPE30K48 allows operation over a wide ambient temperature range with minimal derating.



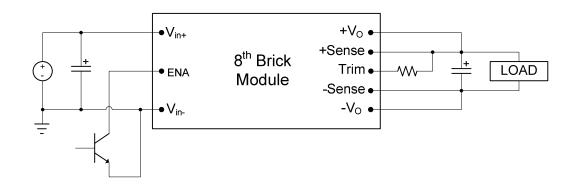
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# **APPLICATION DIAGRAM**





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#### **ELECTRICAL SPECIFICATIONS**

#### 36-75Vin, 1.2V/30Aout

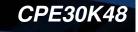
Conditions: T<sub>A</sub> = 25 °C, Airflow = 300 LFM, Vin = 48 VDC, Cin = 33  $\mu$ F, unless otherwise specified.

Input Characteristics					
Parameter	Conditions	Min	Тур	Max	Unit
Operating Input Voltage Range		36	48	75	VDC
Input Under-Voltage Lock-out Turn-on Threshold Turn-off Threshold		34.2 32.4	35 33.2	35.9 34.1	VDC
Input Voltage Transient	100ms			100	VDC
Maximum Input Current	V <sub>IN</sub> = 36VDC; I <sub>out</sub> = 30A			1.22	Α
Input Standby Current	Converter Disabled		2	5	mA
Input No-Load Current	Converter Enabled		45		mA
Short Circuit Input Current	RMS		30		mA
Input Reflected Ripple Current	5Hz to 50MHz See Fig 11 for setup		5	10	mА <sub>РК-РК</sub>
Input Voltage Ripple Rejection	120Hz		50		dB
Inrush Current	rush Current All		-	0.01	A²/s
Output Characteristics					
Parameter	Conditions	Min	Тур	Max	Unit
Output Voltage Set point	Sense pins connected to output pins	1.182	1.2	1.218	VDC
Output Current		0		30	Α
Output Current Limit Inception		32	37	42	Α
Peak Short-Circuit Current	<b>10m</b> $\Omega$ Short			45	Α
RMS Short-Circuit Current	<b>10m</b> $\Omega$ Short			5	A <sub>RMS</sub>
External Load Capacitance		0		20000	uF
Output Ripple and Noise	20MHz Bandwidth 1 uF Ceramic + 22 uF Ceramic See Fig 12 for setup		25	50	mV <sub>PK-PK</sub>
Output Regulation Line: Load: Overall Output Regulation:	Over line, load & temp.	1.176	±2 ±2	±5 ±5 1.224	mV mV V



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# Technical Datasheet



#### **ELECTRICAL SPECIFICATIONS (continued)**

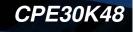
#### 36–75Vin, 1.2V/30Aout

Conditions: T<sub>A</sub> = 25 °C, Airflow = 300 LFM, Vin = 48 VDC, Cin = 33  $\mu$ F, unless otherwise specified.

Absolute Maximum Ratings					
Parameter	Conditions	Min	Тур	Max	Unit
Input Voltage	Continuous Operation	0		75	VDC
Operating Ambient Temperature	With Derating	-40		85	°C
Operating Temperature	T <sub>ref</sub> , see Thermal Derating section	-40		+123	°C
Storage Temperature		-55		+125	°C
Feature Characteristics					
Parameter	Conditions	Min	Тур	Мах	Unit
Switching Frequency			350		kHz
Output Voltage Trim Range <sup>1</sup>		-10		+20	%Vo
Remote Sense Compensation <sup>1</sup>				+10	%
Output Over-voltage Protection	Non-latching	115	125	140	%
Over-temperature Protection	Avg. PCB temp, non-latching		135		°C
Peak Backdrive Output Current during startup into prebiased output	Sinking current from external voltage source equal to $V_{OUT} - 0.5V$ and connected to the output via 1 $\Omega$ resistor. C <sub>OUT</sub> =220µF, Aluminum		500		mA
Backdrive Output Current in OFF state	Converter disabled		0	5	mA
Enable to Output Turn-ON Time	$V_{OUT} = 0.9 * V_{OUT_NOM}$		20		ms
Output Enable ON/OFF Negative Enable Converter ON Converter OFF Positive Enable	All voltages are WRT –Vin. Converter has internal	-0.5 2.4		0.8 20	VDC VDC
Converter ON Converter OFF Enable Pin Current Source/Sink	pull-up of approx. 5V	2.4 -0.5	0.25	20 0.8 1	VDC VDC mA
Output Voltage Overshoot @ Startup			0	2	%Vo
Auto-Restart Period	(all protection		100		ms



# Technical Datasheet



# ELECTRICAL SPECIFICATIONS (continued)

36–75Vin, 1.2V/30Aout

Conditions: Ta = 25 °C, Airflow = 300 LFM, Vin = 48 VDC, Cin=33  $\mu$ F, unless otherwise specified.

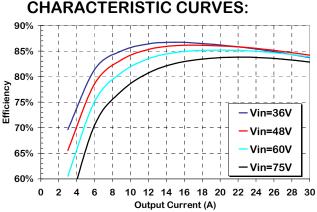
Efficiency					
Parameter	Conditions	Min	Тур	Max	Unit
Full Load	Vin = 48Vin	83	84		%
50% Load	vin = 48 vin	84	86		%
Dynamic Response					
Parameter	Conditions	Min	Тур	Мах	Unit
Load Change 50%-75% or 25% to 50% of lout Max, di/dt = 0.2 A/µs	Co = 1 µF ceramic + 22 µF ceramic		100	150	mV
Settling Time to 1% of Vout			50		μs
Load Change 50%-100% of lout Max, di/dt = 1A/µs	Co = 1 µF ceramic		100	150	mV
Settling Time to 1% of Vout	+ 2000 µF Oscon		50		μs
Isolation Specifications	•				
Isolation Capacitance			1000		рF
Isolation Resistance		10			MΩ
	Input to Output - Open frame	2250			V <sub>DC</sub>
Isolation Voltage	Input to Output - Baseplate	2250			V <sub>DC</sub>
	Input to baseplate	1500			$V_{\text{DC}}$
	Output to baseplate	1000			$V_{\text{DC}}$
Reliability					
Per Telcordia SR-332, Issue 2: Method I, Case 3	MTFB	3,774,635			Hours
(I <sub>o</sub> =80% of I <sub>o</sub> _max, T <sub>A</sub> =40°C, airflow = 200 lfm, 90% confidence)	FITs (failures in 10 <sup>9</sup> hours)	265			/10 <sup>9</sup> Hours

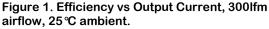
Notes:

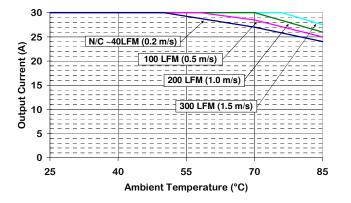
1) Combination of remote sense + trim up not to exceed 20% of Vo<sub>nom</sub>.

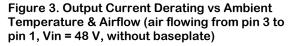


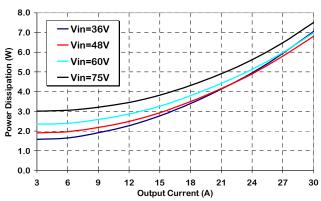


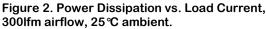


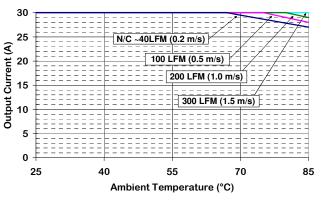


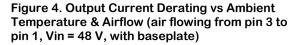














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#### CHARACTERISTIC WAVEFORMS:

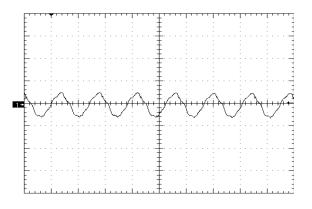


Figure 5. Output Voltage Ripple (20mV/div), time scale – 2uS/div. Vin=Vin\_nom, full resistive.

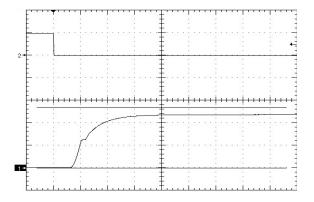


Figure 7. Startup Waveform via Enable Pin, time scale 10mS/div. Vin=Vin\_nom, no load + 2200uF Ch1=0.5V/div,Ch2=5V/div

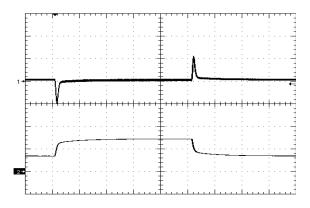


Figure 9. Load Transient Response (100mV/div), di/dt=0.2A/uS, 25% - 50% - 25% of full load, time scale: 200uS/div.

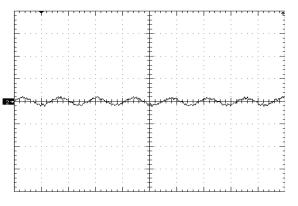


Figure 6. Input Reflected Ripple Current (10mA/div) time scale - 2uS/div. Vin=Vin\_nom, full resistive.

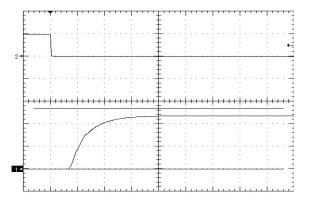


Figure 8. Startup Waveform via Line Voltage, time scale 10mS/div. Vin=Vin\_nom, full resistive load + 10000uF. Ch1=0.5V/div,Ch2=5V/div

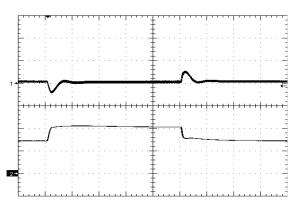


Figure 10. Load Transient Response (100mV/div), di/dt=1A/uS, 25% - 75% - 25% of full load +2000uF output capacitance, time scale: 200uS/div



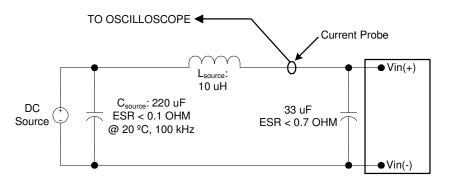
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## **Application Notes**

#### Input Voltage Reflected Ripple Measurement

• INPUT REFLECTED RIPPLE TEST SETUP:

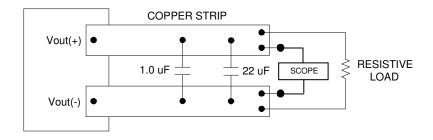


Note: Measure input reflected-ripple current with a simulated source inductance (Ltest) of 10 uH. Capacitor  $C_8$  offsets possible source impedance.

Figure 11. Input Reflected-ripple Current Test Setup.

#### **Output Voltage Ripple Measurement**

• OUTPUT RIPPLE TEST SETUP:



Note: Use a 1µF X7R ceramic capacitor and a 22µF X7R ceramic capacitor. Scope measurement should be made using a BNC socket. Position the load 3 in. [76mm] from module.

Figure 12. Peak-to-Peak Output Noise Measurement Test Setup.



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#### **Output Voltage Trim**

Output voltage adjustment is accomplished by connecting an external resistor between the Trim Pin and either the +Sense or -Sense pins.

#### **TRIM UP EQUATION:**

$$R_{\text{trim\_up}} = \left[\frac{5.1 \times \text{Vo\_nom} \times (100 + \Delta\%)}{0.6 \times \Delta\%} - \frac{510}{\Delta\%} - 10.2\right] \times k\Omega$$

Where  $R_{trim\_up}$  is the resistance value in k-ohms and  $\Delta\%$  is the percent change in the output voltage. E.g. to

 $\left[\frac{5.1 \times 1.2 \times (100 + 10)}{0.6 \times 10} - \frac{510}{10} - 10.2\right] \times k\Omega$  $R_{trim_up} =$ trim the output up 10% or R<sub>trim\_up</sub> = 51kOhm.

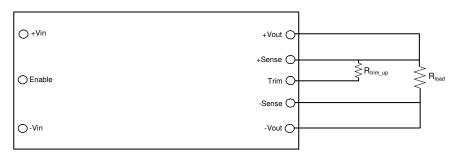


Figure 13. Trim UP circuit configuration

#### **TRIM-DOWN EQUATION:**

$$R_{\text{trim\_down}} = \left(\frac{510}{\Delta\%} - 10.2\right) \times k\Omega$$

Where  $R_{trim\_down}$  is the resistance value in k ohms and  $\Delta\%$  is the percent change in the output voltage.

O +Vin	+Vout ()-	
C Enable	+Sense O-	
Cenable	Trim ()- -Sense ()-	R <sub>trim_down</sub>
O-Vin	-Vout ()-	

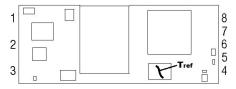






#### **Thermal Derating**

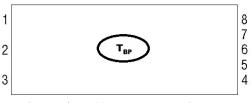
- It is preferable that the DC-DC module have an unobstructed flow of air across it for best thermal performance. Components taller than ~ 2mm in front of the module can deflect airflow and possibly create hotspots.
- Significant cooling is achieved through conductive flow from the modules I/O pins to the host PCB. Sufficiently large traces connecting the dc-dc converter to the source and load will help ensure thermal derating performance will meet or exceed the derating curves published in this datasheet.
- If the module is expected to be operated near the load limits defined in the derating curves, insystem verification of module derating performance should be performed to ensure long-term system reliability. Peak temperatures are to be measured using infrared thermography or by gluing a fine gauge (AWG #40) thermocouple at the T<sub>ref</sub> location(s) shown below. The temperature at the specified location(s) is not to exceed 123°C in order to maintain maximum converter reliability. For baseplate models, T<sub>BP</sub> should not exceed 110°C.





**Open Frame Measurement Point** 

Thermal Image of module @ 48Vin 70C, 200LFM @ Full Load



**Baseplate Measurement Point** 

#### Input Undervoltage Lockout

• The converter is disabled until the input voltage has exceeded the UVLO turn-on threshold. Once the input voltage exceeds this level (see Input Under-Voltage Lock-out in Electrical Specifications table) the module will commence soft-start. Hysteresis minimizes the likelihood of pulling the input voltage below the turn-off threshold during startup which could create an undesirable on/off cycling condition. The converter will continue to operate until the input voltage subsequently falls below the UVLO turn-off threshold.





#### **Enable Pin Function**

- The module has a remote enable function that allows it to be turned on or off remotely. The Enable pin is referenced to the negative input pin (-Vin) of the converter. Modules can be ordered with either negative or positive enable.
- The negative enable option the module will not turn on unless the enable pin is connected to Vin. The positive enable option allows the converter to turn on as soon as voltage sufficient to exceed the UVLO of the converter has been applied to the input terminals. In this case the module is turned off by connecting the Enable pin to –Vin. On/off thresholds are located in the Electrical Specifications table.

#### **Output Overvoltage Protection**

• The module has an independent feedback loop that will disable the output of the converter if a voltage greater than about 125% of the nominal set point is detected. When this threshold is reached, the converter will shut down and remain off for the amount of time specified by the Auto-Restart Period. The converter will attempt a restart once this period of time has elapsed.

#### **Output Overtemperature Protection**

• To provide protection under certain fault conditions, the unit is equipped with a thermal shutdown circuit. The unit will shutdown if the average PCB temperature exceeds approx. 135°C, but the thermal shutdown is <u>not</u> intended as a guarantee that the unit will survive temperatures beyond its rating. The module will automatically restart once it has cooled below the shutdown temperature minus hysteresis (typically 20 deg C.)

#### SMT Version Layout Considerations (if applicable)

- Copper traces with sufficient cross-section must be provided for all output & input pins. SMT pads tied to internal power/ground planes must have multiple vias around each SMT pad to couple expected current loads from module pins into internal traces/planes. One 0.024" (0.6mm) diameter via for each 4A of expected source or load current must be provided as close to the termination as possible, preferably in the direction of current flow from SMT pad to load. Vias must be at least 0.024" (0.6 mm) away from the SMT pad to prevent solder from flowing into the vias.
- SMT pads on the host card are to be 0.110" (2.79mm) diameter. Solder paste screen opening should be 0.105" diameter and the screen should be 0.006" (0.15 mm) thick (other thicknesses are possible; 0.006" provides a good compromise between solder volume and coplanarity compensation.)

#### **Paralleling Converters**

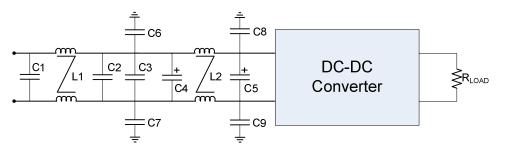
• Modules may be paralleled but it is recommended that the total power draw not exceed the output power rating of a single module. External sharing controllers are recommended for reliability and to ensure equal distribution of the load to the converters.





#### **EMC** Compliance

To meet Class B compliance for EN55022 (CISPR 22) or FCC part 15 sub part j, the following input filter is required:



#### Figure 15. EMI Filter

L1, L2 =	0.77 mH Common Mode Inductor (Pulse P0422)
C1, C2, C3 =	2.2uF ceramic
C4 =	Not used
C5 =	100uF electrolytic
C6, C7 =	8.2nF (@2kV if output is ref. to gnd.)
C8, C9 =	8.2nF (@2kV if output is ref. to gnd.)

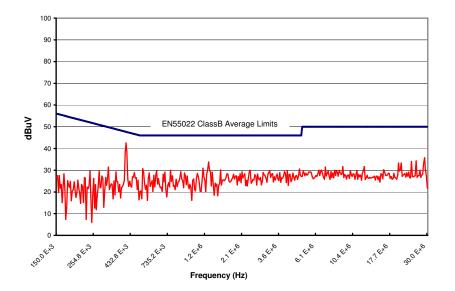


Figure 16. CPE30K48 Conducted Emissions using above specified input filter, Vin = 48V, Full Resistive Load (worst case estimate)



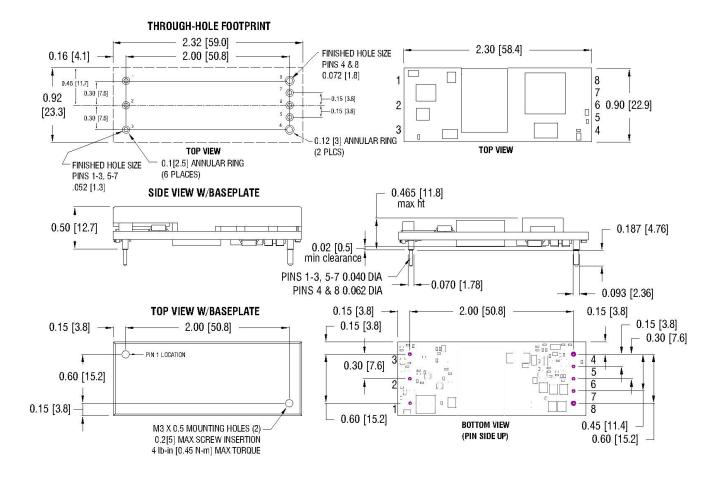
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#### **MODULE PIN ASSIGNMENT:**

PIN #	DESIGNATION	NOTES
1	V <sub>IN</sub> (+)	1) All dimensions in inches [mm]
2	On/Off	Tolerances: .xx ± 0.02 [.x ± .5] .xxx ± 0.010 [.xx ± .25]
3	V <sub>IN</sub> (-)	2) Input, on/off control and sense/trim pins are Ø 0.040" [1.02]
4	V <sub>out</sub> (-)	with Ø 0.070" [1.77] standoff shoulders. 3) Output pins are Ø 1.57 mm (0.062") with Ø 0.093" [2.36]
5	Sense (-)	shoulders (note, shoulder sits .008" above mounting surface)
6	Trim	4) All pins are gold plated with nickel under plating.
7	Sense (+)	5) Weight: 22.4 g (0.79 oz.) open frame 39.1 g (1.38 oz.) baseplate model
8	V <sub>OUT</sub> (+)	6) Workmanship: Meet or exceeds IPC-A-610 Class II

#### **MECHANICAL OUTLINE:**





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ORDERING INFORMATION:						
Product Identifier	Output Current	Output Voltage	Input Voltage	Enable logic option	Additional features	
CPE	30	к	48	N or P	В	
"Cool Power Eighth"	30A	1.2V	36 – 75V	N = Negative P = Positive	B = Baseplate Option	

Rev 1.1, 16-December-15

